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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	24KB (8K x 24)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/dspic30f3012t-20e-ml">https://www.e-xfl.com/product-detail/microchip-technology/dspic30f3012t-20e-ml</a>

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## 2.2 Pins Used During Programming

The pins identified in [Table 2-1](#) are used for device programming. Refer to the appropriate device data sheet for complete pin descriptions.

**TABLE 2-1: dsPIC30F PIN DESCRIPTIONS DURING PROGRAMMING**

Pin Name	Pin Type	Pin Description
MCLR/VPP	P	Programming Enable
VDD	P	Power Supply
VSS	P	Ground
PGC	I	Serial Clock
PGD	I/O	Serial Data

**Legend:** I = Input, O = Output, P = Power

## 2.3 Program Memory Map

The program memory space extends from 0x0 to 0xFFFFFE. Code storage is located at the base of the memory map and supports up to 144 Kbytes (48K instruction words). Code is stored in three, 48 Kbyte memory panels that reside on-chip. [Table 2-2](#) shows the location and program memory size of each device.

Locations 0x800000 through 0x8005BE are reserved for executive code memory. This region stores either the programming executive or debugging executive. The programming executive is used for device programming, while the debug executive is used for in-circuit debugging. This region of memory cannot be used to store user code.

Locations 0xF80000 through 0xF8000E are reserved for the Configuration registers. The bits in these registers may be set to select various device options, and are described in [Section 5.7 “Configuration Bits Programming”](#).

Locations 0xFF0000 and 0xFF0002 are reserved for the Device ID registers. These bits can be used by the programmer to identify what device type is being programmed and are described in [Section 10.0 “Device ID”](#). The device ID reads out normally, even after code protection is applied.

[Figure 2-2](#) illustrates the memory map for the dsPIC30F devices.

## 2.4 Data EEPROM Memory

The Data EEPROM array supports up to 4 Kbytes of data and is located in one memory panel. It is mapped in program memory space, residing at the end of User Memory Space (see [Figure 2-2](#)). [Table 2-2](#) shows the location and size of data EEPROM in each device.

**TABLE 2-2: CODE MEMORY AND DATA EEPROM MAP AND SIZE**

Device	Code Memory map (Size in Instruction Words)	Data EEPROM Memory Map (Size in Bytes)
dsPIC30F2010	0x000000-0x001FFE (4K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F2011	0x000000-0x001FFE (4K)	None (0K)
dsPIC30F2012	0x000000-0x001FFE (4K)	None (0K)
dsPIC30F3010	0x000000-0x003FFE (8K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F3011	0x000000-0x003FFE (8K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F3012	0x000000-0x003FFE (8K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F3013	0x000000-0x003FFE (8K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F3014	0x000000-0x003FFE (8K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F4011	0x000000-0x007FFE (16K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F4012	0x000000-0x007FFE (16K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F4013	0x000000-0x007FFE (16K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F5011	0x000000-0x00AFFE (22K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F5013	0x000000-0x00AFFE (22K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F5015	0x000000-0x00AFFE (22K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F5016	0x000000-0x00AFFE (22K)	0x7FFC00-0x7FFFFE (1K)
dsPIC30F6010	0x000000-0x017FFE (48K)	0x7FF000-0x7FFFFE (4K)
dsPIC30F6010A	0x000000-0x017FFE (48K)	0x7FF000-0x7FFFFF (4K)
dsPIC30F6011	0x000000-0x015FFE (44K)	0x7FF800-0x7FFFFE (2K)
dsPIC30F6011A	0x000000-0x015FFE (44K)	0x7FF800-0x7FFFFE (2K)
dsPIC30F6012	0x000000-0x017FFE (48K)	0x7FF000-0x7FFFFE (4K)
dsPIC30F6012A	0x000000-0x017FFE (48K)	0x7FF000-0x7FFFFE (4K)
dsPIC30F6013	0x000000-0x015FFE (44K)	0x7FF800-0x7FFFFE (2K)
dsPIC30F6013A	0x000000-0x015FFE (44K)	0x7FF800-0x7FFFFE (2K)
dsPIC30F6014	0x000000-0x017FFE (48K)	0x7FF000-0x7FFFFE (4K)
dsPIC30F6014A	0x000000-0x017FFE (48K)	0x7FF000-0x7FFFFE (4K)
dsPIC30F6015	0x000000-0x017FFE (48K)	0x7FF000-0x7FFFFE (4K)

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**TABLE 5-6: FOSC CONFIGURATION BITS DESCRIPTION FOR dsPIC30F2011/2012, dsPIC30F3010/3011/3012/3013/3014, dsPIC30F4013, dsPIC30F5015/5016, dsPIC30F6010A/6011A/6012A/6013A/6014A AND dsPIC30F6015 (CONTINUED)**

Bit Field	Register	Description
FPR<4:0>	FOSC	<b>Alternate Oscillator Mode (when FOS&lt;2:0&gt; = 011b)</b> 1xxxx = Reserved (do not use) 0111x = Reserved (do not use) 01101 = Reserved (do not use) 01100 = ECIO – External clock. OSC2 pin is I/O 01011 = EC – External clock. OSC2 pin is system clock output (Fosc/4) 01010 = Reserved (do not use) 01001 = ERC – External RC oscillator. OSC2 pin is system clock output (Fosc/4) 01000 = ERCIO – External RC oscillator. OSC2 pin is I/O 00111 = Reserved (do not use) 00110 = Reserved (do not use) 00101 = Reserved (do not use) 00100 = XT – XT crystal oscillator (4 MHz-10 MHz crystal) 00010 = HS – HS crystal oscillator (10 MHz-25 MHz crystal) 00001 = Reserved (do not use) 00000 = XTL – XTL crystal oscillator (200 kHz-4 MHz crystal)

**TABLE 5-8: dsPIC30F CONFIGURATION REGISTERS (FOR dsPIC30F2010, dsPIC30F4011/4012 AND dsPIC30F6010/ 6011/6012/6013/ 6014)**

Address	Name	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0xF80000	FOSC	FCKSM<1:0>		—	—	—	—	FOS<1:0>		—	—	—	—	FPR<3:0>			
0xF80002	FWDT	FWDTEN	—	—	—	—	—	—	—	—	—	FWPSA<1:0>		FWPSB<3:0>			
0xF80004	FBORPOR	MCLREN	—	—	—	—	PWMPIN <sup>(1)</sup>	HPOL <sup>(1)</sup>	LPOL <sup>(1)</sup>	BOREN	—	BORV<1:0>		—	—	FPWRT<1:0>	
0xF80006	FBS	—	—	Reserved <sup>(2)</sup>		—	—	—	Reserved <sup>(2)</sup>	—	—	—	—	Reserved <sup>(2)</sup>			
0xF80008	FSS	—	—	Reserved <sup>(2)</sup>		—	—	Reserved <sup>(2)</sup>		—	—	—	—	Reserved <sup>(2)</sup>			
0xF8000A	FGS	—	—	—	—	—	—	—	—	—	—	—	—	—	Reserved <sup>(2)</sup>	GCP	GWRP
0xF8000C	FICD	BKBUG	COE	—	—	—	—	—	—	—	—	—	—	—	—	ICS<1:0>	

**Note 1:** On the 6011, 6012, 6013 and 6014, these bits are reserved (read as '1' and must be programmed as '1').

**Note 2:** Reserved bits read as '1' and must be programmed as '1'.

**TABLE 5-9: dsPIC30F CONFIGURATION REGISTERS (FOR dsPIC30F5011/5013)**

Address	Name	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0xF80000	FOSC	FCKSM<1:0>		—	—	—	—	FOS<1:0>		—	—	—	—	FPR<3:0>			
0xF80002	FWDT	FWDTEN	—	—	—	—	—	—	—	—	—	FWPSA<1:0>		FWPSB<3:0>			
0xF80004	FBORPOR	MCLREN	—	—	—	—	Reserved <sup>(1)</sup>			BOREN	—	BORV<1:0>		—	—	FPWRT<1:0>	
0xF80006	FBS	—	—	RBS<1:0>		—	—	—	EBS	—	—	—	—	BSS<2:0>			BWRP
0xF80008	FSS	—	—	RSS<1:0>		—	—	ESS<1:0>		—	—	—	—	SSS<2:0>			SWRP
0xF8000A	FGS	—	—	—	—	—	—	—	—	—	—	—	—	—	GSS<1:0>		GWRP
0xF8000C	FICD	BKBUG	COE	—	—	—	—	—	—	—	—	—	—	—	—	ICS<1:0>	

**Note 1:** Reserved bits read as '1' and must be programmed as '1'.

**TABLE 5-10: dsPIC30F CONFIGURATION REGISTERS (FOR dsPIC30F2011/2012, dsPIC30F3010/3011/3012/3013/3014, dsPIC30F4013 AND dsPIC30F5015/5016)**

Address	Name	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0xF80000	FOSC	FCKSM<1:0>		—	—	—	FOS<2:0>			—	—	—	FPR<4:0>				
0xF80002	FWDT	FWDTEN	—	—	—	—	—	—	—	—	—	FWPSA<1:0>		FWPSB<3:0>			
0xF80004	FBORPOR	MCLREN	—	—	—	—	PWMPIN <sup>(1)</sup>	HPOL <sup>(1)</sup>	LPOL <sup>(1)</sup>	BOREN	—	BORV<1:0>		—	—	FPWRT<1:0>	
0xF80006	FBS	—	—	Reserved <sup>(2)</sup>		—	—	—	Reserved <sup>(2)</sup>	—	—	—	—	Reserved <sup>(2)</sup>			
0xF80008	FSS	—	—	Reserved <sup>(2)</sup>		—	—	Reserved <sup>(2)</sup>		—	—	—	—	Reserved <sup>(2)</sup>			
0xF8000A	FGS	—	—	—	—	—	—	—	—	—	—	—	—	—	Reserved <sup>(3)</sup>	GCP	GWRP
0xF8000C	FICD	BKBUG	COE	—	—	—	—	—	—	—	—	—	—	—	—	ICS<1:0>	

**Note** 1: On the 2011, 2012, 3012, 3013, 3014 and 4013, these bits are reserved (read as '1' and must be programmed as '1').  
2: Reserved bits read as '1' and must be programmed as '1'.  
3: The FGS<2> bit is a read-only copy of the GCP bit (FGS<1>).

**TABLE 5-11: dsPIC30F CONFIGURATION REGISTERS (FOR dsPIC30F6010A/6011A/6012A/6013A/6014A AND dsPIC30F6015)**

Address	Name	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0xF80000	FOSC	FCKSM<1:0>		—	—	—	FOS<2:0>			—	—	—	FPR<4:0>				
0xF80002	FWDT	FWDTEN	—	—	—	—	—	—	—	—	—	FWPSA<1:0>		FWPSB<3:0>			
0xF80004	FBORPOR	MCLREN	—	—	—	—	PWMPIN <sup>(1)</sup>	HPOL <sup>(1)</sup>	LPOL <sup>(1)</sup>	BOREN	—	BORV<1:0>		—	—	FPWRT<1:0>	
0xF80006	FBS	—	—	RBS<1:0>		—	—	—	EBS	—	—	—	—	BSS<2:0>			BWRP
0xF80008	FSS	—	—	RSS<1:0>		—	—	ESS<1:0>		—	—	—	—	SSS<2:0>			SWRP
0xF8000A	FGS	—	—	—	—	—	—	—	—	—	—	—	—	—	GSS<1:0>		GWRP
0xF8000C	FICD	BKBUG	COE	—	—	—	—	—	—	—	—	—	—	—	—	ICS<1:0>	

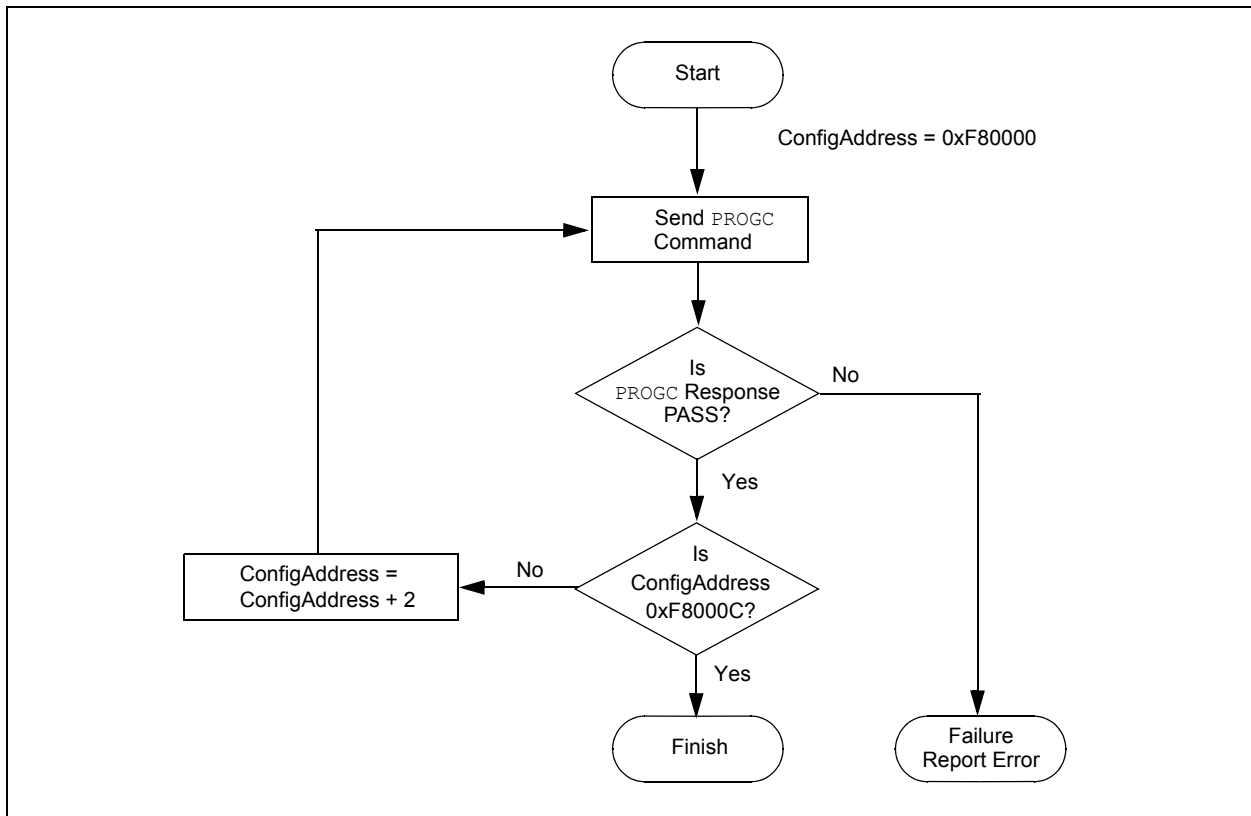
**Note** 1: On the 6011A, 6012A, 6013A and 6014A, these bits are reserved (read as '1' and must be programmed as '1').

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## 5.8 Exiting Enhanced ICSP Mode

The Enhanced ICSP mode is exited by removing power from the device or bringing MCLR to VIL. When normal user mode is next entered, the program that was stored using Enhanced ICSP will execute.

**FIGURE 5-5: CONFIGURATION BIT PROGRAMMING FLOW**



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clocked out. The programmer can begin to clock out the response 20  $\mu$ sec after PGD is brought low, and it must provide the necessary amount of clock pulses to receive the entire response from the programming executive.

Once the entire response is clocked out, the programmer should terminate the clock on PGC until it is time to send another command to the programming executive. This protocol is illustrated in Figure 7-2.

## 7.3 SPI Rate

In Enhanced ICSP mode, the dsPIC30F operates from the fast internal RC oscillator, which has a nominal frequency of 7.37 MHz. This oscillator frequency yields an effective system clock frequency of 1.84 MHz. Since the SPI module operates in Slave mode, the programmer must limit the SPI clock rate to a frequency no greater than 1 MHz.

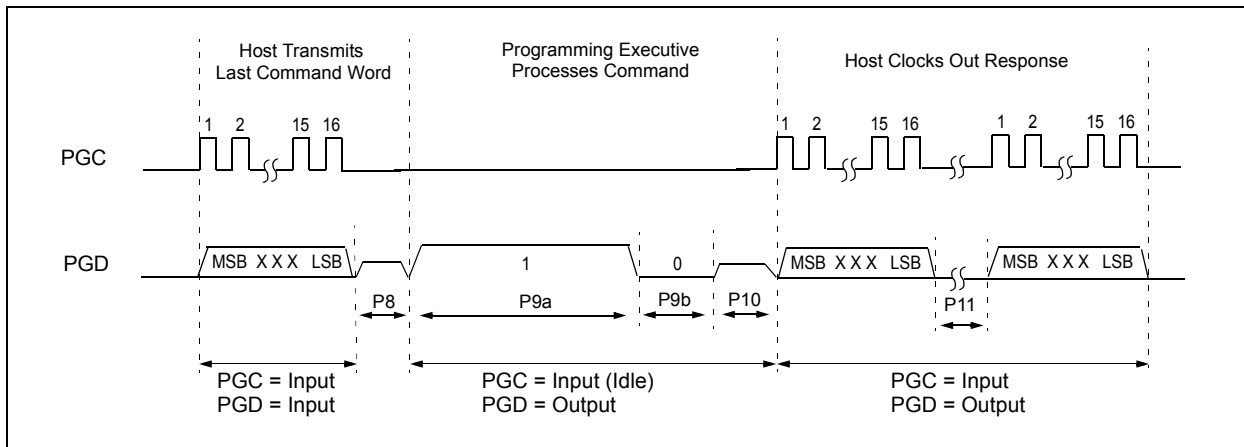
**Note:** If the programmer provides the SPI with a clock faster than 1 MHz, the behavior of the programming executive will be unpredictable.

## 7.4 Time Outs

The programming executive uses no Watchdog Timer or time out for transmitting responses to the programmer. If the programmer does not follow the flow control mechanism using PGC, as described in [Section 7.2 “Communication Interface and Protocol”](#), it is possible that the programming executive will behave unexpectedly while trying to send a response to the programmer. Since the programming executive has no time out, it is imperative that the programmer correctly follow the described communication protocol.

As a safety measure, the programmer should use the command time outs identified in [Table 8-1](#). If the command time out expires, the programmer should reset the programming executive and start programming the device again.

**FIGURE 7-2: PROGRAMMING EXECUTIVE – PROGRAMMER COMMUNICATION PROTOCOL**



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TABLE 8-1: PROGRAMMING EXECUTIVE COMMAND SET

Opcode	Mnemonic	Length (16-bit words)	Time Out	Description
0x0	SCHECK	1	1 ms	Sanity check.
0x1	READD	4	1 ms/row	Read N 16-bit words of data EEPROM, Configuration registers or device ID starting from specified address.
0x2	READP	4	1 ms/row	Read N 24-bit instruction words of code memory starting from specified address.
0x3	Reserved	N/A	N/A	This command is reserved. It will return a NACK.
0x4	PROGD <sup>(2)</sup>	19	5 ms	Program one row of data EEPROM at the specified address, then verify.
0x5	PROGP <sup>(1)</sup>	51	5 ms	Program one row of code memory at the specified address, then verify.
0x6	PROGC	4	5 ms	Write byte or 16-bit word to specified Configuration register.
0x7	ERASEB	2	5 ms	Bulk Erase (entire code memory or data EEPROM), or erase by segment.
0x8	ERASED <sup>(2)</sup>	3	5 ms/row	Erase rows of data EEPROM from specified address.
0x9	ERASEP <sup>(1)</sup>	3	5 ms/row	Erase rows of code memory from specified address.
0xA	QBLANK	3	300 ms	Query if the code memory and data EEPROM are blank.
0xB	QVER	1	1 ms	Query the programming executive software version.

**Note 1:** One row of code memory consists of (32) 24-bit words. Refer to [Table 5-2](#) for device-specific information.

**Note 2:** One row of data EEPROM consists of (16) 16-bit words. Refer to [Table 5-3](#) for device-specific information.



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## 8.5.3 READP COMMAND

15	12	11	8	7	0
Opcode		Length			
N					
Reserved			Addr_MSB		
Addr_LS					

Field	Description
Opcode	0x2
Length	0x4
N	Number of 24-bit instructions to read (max of 32768)
Reserved	0x0
Addr_MSB	MSB of 24-bit source address
Addr_LS	LS 16 bits of 24-bit source address

The **READP** command instructs the programming executive to read N 24-bit words of code memory starting from the 24-bit address specified by Addr\_MSB and Addr\_LS. This command can only be used to read 24-bit data. All data returned in response to this command uses the packed data format described in [Section 8.3 “Packed Data Format”](#).

### Expected Response (2 + 3 \* N/2 words for N even):

0x1200

2 + 3 \* N/2

Least significant program memory word 1

...

Least significant data word N

### Expected Response (4 + 3 \* (N – 1)/2 words for N odd):

0x1200

4 + 3 \* (N – 1)/2

Least significant program memory word 1

...

MSB of program memory word N (zero padded)

**Note:** Reading unimplemented memory will cause the programming executive to reset.

## 8.5.4 PROGD COMMAND

15	12	11	8	7	0
Opcode		Length			
Reserved			Addr_MSB		
Addr_LS					
D_1					
D_2					
...					
D_16					

Field	Description
Opcode	0x4
Length	0x13
Reserved	0x0
Addr_MSB	MSB of 24-bit destination address
Addr_LS	LS 16 bits of 24-bit destination address
D_1	16-bit data word 1
D_2	16-bit data word 2
...	16-bit data words 3 through 15
D_16	16-bit data word 16

The **PROGD** command instructs the programming executive to program one row of data EEPROM. The data to be programmed is specified by the 16 data words (D\_1, D\_2,..., D\_16) and is programmed to the destination address specified by Addr\_MSB and Addr\_LSB. The destination address should be a multiple of 0x20.

Once the row of data EEPROM has been programmed, the programming executive verifies the programmed data against the data in the command.

### Expected Response (2 words):

0x1400

0x0002

**Note:** Refer to [Table 5-3](#) for data EEPROM size information.

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## 8.5.5 PROGP COMMAND

15	12	11	8	7	0
Opcode		Length			
Reserved			Addr_MSB		
Addr_LS					
D_1					
D_2					
...					
D_N					

Field	Description
Opcode	0x5
Length	0x33
Reserved	0x0
Addr_MSB	MSB of 24-bit destination address
Addr_LS	LS 16 bits of 24-bit destination address
D_1	16-bit data word 1
D_2	16-bit data word 2
...	16-bit data word 3 through 47
D_48	16-bit data word 48

The **PROGP** command instructs the programming executive to program one row of code memory (32 instruction words) to the specified memory address. Programming begins with the row address specified in the command. The destination address should be a multiple of 0x40.

The data to program to memory, located in command words D\_1 through D\_48, must be arranged using the packed instruction word format shown in [Figure 8-2](#).

After all data has been programmed to code memory, the programming executive verifies the programmed data against the data in the command.

### Expected Response (2 words):

0x1500  
0x0002

**Note:** Refer to [Table 5-2](#) for code memory size information.

## 8.5.6 PROGC COMMAND

15	12	11	8	7	0
Opcode		Length			
Reserved			Addr_MSB		
Addr_LS					
Data					

Field	Description
Opcode	0x6
Length	0x4
Reserved	0x0
Addr_MSB	MSB of 24-bit destination address
Addr_LS	LS 16 bits of 24-bit destination address
Data	Data to program

The **PROGC** command programs data to the specified Configuration register and verifies the programming. Configuration registers are 16 bits wide, and this command allows one Configuration register to be programmed.

### Expected Response (2 words):

0x1600  
0x0002

**Note:** This command can only be used for programming Configuration registers.

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## 8.5.7 ERASEB COMMAND

15	12	11		2	0
Opcode		Length			
Reserved					MS

Field	Description
Opcode	0x7
Length	0x2
Reserved	0x0
MS	Select memory to erase: 0x0 = All Code in General Segment 0x1 = All Data EEPROM in General Segment 0x2 = All Code and Data EEPROM in General Segment, interrupt vectors and FGS Configuration register 0x3 = Full Chip Erase 0x4 = All Code and Data EEPROM in Boot, Secure and General Segments, and FBS, FSS and FGS Configuration registers 0x5 = All Code and Data EEPROM in Secure and General Segments, and FSS and FGS Configuration registers 0x6 = All Data EEPROM in Boot Segment 0x7 = All Data EEPROM in Secure Segment

The **ERASEB** command performs a Bulk Erase. The MS field selects the memory to be bulk erased, with options for erasing Code and/or Data EEPROM in individual memory segments.

When Full Chip Erase is selected, the following memory regions are erased:

- All code memory (even if code-protected)
- All data EEPROM
- All code-protect Configuration registers

Only the executive code memory, Unit ID, device ID and Configuration registers that are not code-protected remain intact after a Chip Erase.

### Expected Response (2 words):

0x1700  
0x0002

**Note:** A Full Chip Erase cannot be performed in low-voltage programming systems ( $V_{DD}$  less than 4.5 volts). **ERASED** and **ERASEP** must be used to erase code memory, executive memory and data memory. Alternatively, individual Segment Erase operations may be performed.

## 8.5.8 ERASED COMMAND

15	12	11		8	7		0
Opcode		Length					
Num_Rows				Addr_MSB			
Addr_LS							

Field	Description
Opcode	0x8
Length	0x3
Num_Rows	Number of rows to erase (max of 128)
Addr_MSB	MSB of 24-bit base address
Addr_LS	LS 16 bits of 24-bit base address

The **ERASED** command erases the specified number of rows of data EEPROM from the specified base address. The specified base address must be a multiple of 0x20. Since the data EEPROM is mapped to program space, a 24-bit base address must be specified.

After the erase is performed, all targeted bytes of data EEPROM will contain 0xFF.

### Expected Response (2 words):

0x1800  
0x0002

**Note:** The **ERASED** command cannot be used to erase the Configuration registers or device ID. Code-protect Configuration registers can only be erased with the **ERASEB** command, while the device ID is read-only.

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## 8.5.11 QVER COMMAND

15	12	11	0
Opcode	Length		

Field	Description
Opcode	0xB
Length	0x1

The QVER command queries the version of the programming executive software stored in test memory. The “version.revision” information is returned in the response’s QE\_Code using a single byte with the following format: main version in upper nibble and revision in the lower nibble (i.e., 0x23 is version 2.3 of programming executive software).

### Expected Response (2 words):

0x1BMN (where “MN” stands for version M.N)  
0x0002

## 9.0 PROGRAMMING EXECUTIVE RESPONSES

### 9.1 Overview

The programming executive sends a response to the programmer for each command that it receives. The response indicates if the command was processed correctly, and includes any required response or error data.

The programming executive response set is shown in Table 9-1. This table contains the opcode, mnemonic and description for each response. The response format is described in Section 9.2 “Response Format”.

**TABLE 9-1: PROGRAMMING EXECUTIVE RESPONSE SET**

Opcode	Mnemonic	Description
0x1	PASS	Command successfully processed.
0x2	FAIL	Command unsuccessfully processed.
0x3	NACK	Command not known.

## 9.2 Response Format

As shown in Example 9-1, all programming executive responses have a general format consisting of a two word header and any required data for the command. Table 9-2 lists the fields and their descriptions.

**EXAMPLE 9-1: FORMAT**

15	12	11	8	7	0
Opcode	Last_Cmd		QE_Code		
Length					
D_1 (if applicable)					
...					
D_N (if applicable)					

**TABLE 9-2: FIELDS AND DESCRIPTIONS**

Field	Description
Opcode	Response opcode.
Last_Cmd	Programmer command that generated the response.
QE_Code	Query code or Error code.
Length	Response length in 16-bit words (includes 2 header words.)
D_1	First 16-bit data word (if applicable).
D_N	Last 16-bit data word (if applicable).

### 9.2.1 Opcode FIELD

The Opcode is a 4-bit field in the first word of the response. The Opcode indicates how the command was processed (see Table 9-1). If the command is processed successfully, the response opcode is PASS. If there is an error in processing the command, the response opcode is FAIL, and the QE\_Code indicates the reason for the failure. If the command sent to the programming executive is not identified, the programming executive returns a NACK response.

### 9.2.2 Last\_Cmd FIELD

The Last\_Cmd is a 4-bit field in the first word of the response and indicates the command that the programming executive processed. Since the programming executive can only process one command at a time, this field is technically not required. However, it can be used to verify whether the programming executive correctly received the command that the programmer transmitted.

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## 9.2.3 QE\_Code FIELD

The QE\_Code is a byte in the first word of the response. This byte is used to return data for query commands, and error codes for all other commands.

When the programming executive processes one of the two query commands (`QBLANK` or `QVER`), the returned opcode is always PASS and the QE\_Code holds the query response data. The format of the QE\_Code for both queries is shown in [Table 9-3](#).

**TABLE 9-3: QE\_Code FOR QUERIES**

Query	QE_Code
QBLANK	0x0F = Code memory and data EEPROM are NOT blank 0xF0 = Code memory and data EEPROM are blank
QVER	0xMN, where programming executive software version = M.N (i.e., 0x32 means software version 3.2)

When the programming executive processes any command other than a Query, the QE\_Code represents an error code. Supported error codes are shown in [Table 9-4](#). If a command is successfully processed, the returned QE\_Code is set to 0x0, which indicates that there was no error in the command processing. If the verify of the programming for the `PROGD`, `PROGP` or `PROGC` command fails, the QE\_Code is set to 0x1. For all other programming executive errors, the QE\_Code is 0x2.

**TABLE 9-4: QE\_Code FOR NON-QUERY COMMANDS**

QE_Code	Description
0x0	No error
0x1	Verify failed
0x2	Other error

## 9.2.4 RESPONSE LENGTH

The response length indicates the length of the programming executive's response in 16-bit words. This field includes the 2 words of the response header.

With the exception of the response for the `READD` and `READP` commands, the length of each response is only 2 words.

The response to the `READD` command is  $N + 2$  words, where  $N$  is the number of words specified in the `READD` command.

The response to the `READP` command uses the packed instruction word format described in [Section 8.3 "Packed Data Format"](#). When reading an odd number of program memory words ( $N$  odd), the response to the `READP` command is  $(3 \cdot (N + 1)/2 + 2)$  words. When reading an even number of program memory words ( $N$  even), the response to the `READP` command is  $(3 \cdot N/2 + 2)$  words.

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## 11.0 ICSP™ MODE

### 11.1 ICSP Mode

ICSP mode is a special programming protocol that allows you to read and write to the dsPIC30F programming executive. The ICSP mode is the second (and slower) method used to program the device. This mode also has the ability to read the contents of executive memory to determine whether the programming executive is present. This capability is accomplished by applying control codes and instructions serially to the device using pins PGC and PGD.

In ICSP mode, the system clock is taken from the PGC pin, regardless of the device's oscillator Configuration bits. All instructions are first shifted serially into an internal buffer, then loaded into the Instruction register and executed. No program fetching occurs from internal memory. Instructions are fed in 24 bits at a time. PGD is used to shift data in and PGC is used as both the serial shift clock and the CPU execution clock.

Data is transmitted on the rising edge and latched on the falling edge of PGC. For all data transmissions, the Least Significant bit (LSb) is transmitted first.

**Note 1:** During ICSP operation, the operating frequency of PGC must not exceed 5 MHz.

**2:** Because ICSP is slower, it is recommended that only Enhanced ICSP (E-ICSP) mode be used for device programming, as described in [Section 5.1 "Overview of the Programming Process"](#).

### 11.2 ICSP Operation

Upon entry into ICSP mode, the CPU is idle. Execution of the CPU is governed by an internal state machine. A 4-bit control code is clocked in using PGC and PGD, and this control code is used to command the CPU (see [Table 11-1](#)).

The SIX control code is used to send instructions to the CPU for execution, while the REGOUT control code is used to read data out of the device via the VISI register. The operation details of ICSP mode are provided in [Section 11.2.1 "SIX Serial Instruction Execution"](#) and [Section 11.2.2 "REGOUT Serial Instruction Execution"](#).

**TABLE 11-1: CPU CONTROL CODES IN ICSP™ MODE**

4-bit Control Code	Mnemonic	Description
0000b	SIX	Shift in 24-bit instruction and execute.
0001b	REGOUT	Shift out the VISI register.
0010b-1111b	N/A	Reserved.

#### 11.2.1 SIX SERIAL INSTRUCTION EXECUTION

The SIX control code allows execution of dsPIC30F assembly instructions. When the SIX code is received, the CPU is suspended for 24 clock cycles as the instruction is then clocked into the internal buffer. Once the instruction is shifted in, the state machine allows it to be executed over the next four clock cycles. While the received instruction is executed, the state machine simultaneously shifts in the next 4-bit command (see [Figure 11-2](#)).

**Note 1:** Coming out of the ICSP entry sequence, the first 4-bit control code is always forced to SIX and a forced NOP instruction is executed by the CPU. Five additional PGC clocks are needed on start-up, thereby resulting in a 9-bit SIX command instead of the normal 4-bit SIX command. After the forced SIX is clocked in, ICSP operation resumes as normal (the next 24 clock cycles load the first instruction word to the CPU). See [Figure 11-1](#) for details.

**2:** TBLRDH, TBLRDL, TBLWTH and TBLWTL instructions must be followed by a NOP instruction.

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**TABLE 11-5: SERIAL INSTRUCTION EXECUTION FOR ERASING PROGRAM MEMORY  
(EITHER IN LOW-VOLTAGE OR NORMAL-VOLTAGE SYSTEMS) (CONTINUED)**

Command (Binary)	Data (Hexadecimal)	Description
<b>Step 6:</b> Update the row address stored in NVMADRU:NVMADR. When W6 rolls over to 0x0, NVMADRU must be incremented.		
0000	430307	ADD W6, W7, W6
0000	AF0042	BTSC SR, #C
0000	EC2764	INC NVMADRU
0000	883B16	MOV W6, NVMADR
<b>Step 7:</b> Reset device internal PC.		
0000	040100	GOTO 0x100
0000	000000	NOP
<b>Step 8:</b> Repeat Steps 3-7 until all rows of code memory are erased.		
<b>Step 9:</b> Initialize NVMADR and NVMADRU to erase executive memory and initialize W7 for row address updates.		
0000	EB0300	CLR W6
0000	883B16	MOV W6, NVMADR
0000	200807	MOV #0x80, W7
0000	883B27	MOV W7, NVMADRU
0000	200407	MOV #0x40, W7
<b>Step 10:</b> Set NVMCON to erase 1 row of executive memory.		
0000	24071A	MOV #0x4071, W10
0000	883B0A	MOV W10, NVMCON
<b>Step 11:</b> Unlock the NVMCON to erase 1 row of executive memory.		
0000	200558	MOV #0x55, W8
0000	883B38	MOV W8, NVMKEY
0000	200AA9	MOV #0xAA, W9
0000	883B39	MOV W9, NVMKEY
<b>Step 12:</b> Initiate the erase cycle.		
0000	A8E761	BSET NVMCON, #WR
0000	000000	NOP
0000	000000	NOP
—	—	Externally time 'P13a' ms (see <a href="#">Section 13.0 “AC/DC Characteristics and Timing Requirements”</a> )
0000	000000	NOP
0000	000000	NOP
0000	A9E761	BCLR NVMCON, #WR
0000	000000	NOP
0000	000000	NOP
<b>Step 13:</b> Update the row address stored in NVMADR.		
0000	430307	ADD W6, W7, W6
0000	883B16	MOV W6, NVMADR
<b>Step 14:</b> Reset device internal PC.		
0000	040100	GOTO 0x100
0000	000000	NOP
<b>Step 15:</b> Repeat Steps 10-14 until all 24 rows of executive memory are erased.		
<b>Step 16:</b> Initialize NVMADR and NVMADRU to erase data memory and initialize W7 for row address updates.		
0000	2XXXX6	MOV #<lower 16-bits of starting Data EEPROM address>, W6
0000	883B16	MOV W6, NVMADR
0000	2007F6	MOV #0x7F, W6
0000	883B16	MOV W6, NVMADRU
0000	200207	MOV #0x20, W7
<b>Step 17:</b> Set NVMCON to erase 1 row of data memory.		
0000	24075A	MOV #0x4075, W10
0000	883B0A	MOV W10, NVMCON

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## 11.11 Reading Configuration Memory

The procedure for reading configuration memory is similar to the procedure for reading code memory, except that 16-bit data words are read instead of 24-bit words. Since there are seven Configuration registers, they are read one register at a time.

Table 11-11 shows the ICSP programming details for reading all of the configuration memory. Note that the TBLPAG register is hard-coded to 0xF8 (the upper byte address of configuration memory), and the read pointer W6 is initialized to 0x0000.

**TABLE 11-11: SERIAL INSTRUCTION EXECUTION FOR READING ALL CONFIGURATION MEMORY**

Command (Binary)	Data (Hexadecimal)	Description
<b>Step 1:</b> Exit the Reset vector.		
0000	040100	GOTO 0x100
0000	040100	GOTO 0x100
0000	000000	NOP
<b>Step 2:</b> Initialize TBLPAG, and the read pointer (W6) and the write pointer (W7) for TBLRD instruction.		
0000	200F80	MOV #0xF8, W0
0000	880190	MOV W0, TBLPAG
0000	EB0300	CLR W6
0000	EB0380	CLR W7
0000	000000	NOP
<b>Step 3:</b> Read the Configuration register and write it to the VISI register (located at 0x784).		
0000	BA0BB6	TBLRDL [W6++], [W7]
0000	000000	NOP
0000	000000	NOP
0000	883C20	MOV W0, VISI
0000	000000	NOP
<b>Step 4:</b> Output the VISI register using the REGOUT command.		
0001	<VISI>	Clock out contents of VISI register
0000	000000	NOP
<b>Step 5:</b> Reset device internal PC.		
0000	040100	GOTO 0x100
0000	000000	NOP
<b>Step 6:</b> Repeat steps 3-5 six times to read all of configuration memory.		



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## 11.13 Reading the Application ID Word

The application ID word is stored at address 0x8005BE in executive code memory. To read this memory location, you must use the SIX control code to move this program memory location to the VISI register. The REGOUT control code must then be used to clock the contents of the VISI register out of the device. The corresponding control and instruction codes that must be serially transmitted to the device to perform this operation are shown in [Table 11-13](#).

Once the programmer has clocked-out the application ID word, it must be inspected. If the application ID has the value 0xBB, the programming executive is resident in memory and the device can be programmed using the mechanism described in [Section 5.0 “Device Programming”](#). However, if the application ID has any other value, the programming executive is not resident in memory. It must be loaded to memory before the device can be programmed. The procedure for loading the programming executive to the memory is described in [Section 12.0 “Programming the Programming Executive to Memory”](#).

## 11.14 Exiting ICSP Mode

After confirming that the programming executive is resident in memory, or loading the programming executive, ICSP mode is exited by removing power to the device or bringing MCLR to V<sub>IL</sub>. Programming can then take place by following the procedure outlined in [Section 5.0 “Device Programming”](#).

**TABLE 11-13: SERIAL INSTRUCTION EXECUTION FOR READING THE APPLICATION ID WORD**

Command (Binary)	Data (Hexadecimal)	Description
<b>Step 1: Exit the Reset vector.</b>		
0000	040100	GOTO 0x100
0000	040100	GOTO 0x100
0000	000000	NOP
<b>Step 2: Initialize TBLPAG and the read pointer (W0) for TBLRD instruction.</b>		
0000	200800	MOV #0x80, W0
0000	880190	MOV W0, TBLPAG
0000	205BE0	MOV #0x5BE, W0
0000	207841	MOV VISI, W1
0000	000000	NOP
0000	BA0890	TBLRD [W0], [W1]
0000	000000	NOP
0000	000000	NOP
<b>Step 3: Output the VISI register using the REGOUT command.</b>		
0001	<VISI>	Clock out contents of the VISI register
0000	000000	NOP

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**TABLE 12-1: PROGRAMMING THE PROGRAMMING EXECUTIVE (CONTINUED)**

Command (Binary)	Data (Hexadecimal)	Description
<b>Step 8:</b> Set the read pointer (W6) and load the (next four write) latches.		
0000	EB0300	CLR W6
0000	000000	NOP
0000	BB0BB6	TBLWTL [W6++], [W7]
0000	000000	NOP
0000	000000	NOP
0000	BBDBB6	TBLWTH.B [W6++], [W7++]
0000	000000	NOP
0000	000000	NOP
0000	BBE6B6	TBLWTH.B [W6++], [W7++]
0000	000000	NOP
0000	000000	NOP
0000	BB1BB6	TBLWTL [W6++], [W7++]
0000	000000	NOP
0000	000000	NOP
0000	BB0BB6	TBLWTL [W6++], [W7]
0000	000000	NOP
0000	000000	NOP
0000	BBDBB6	TBLWTH.B [W6++], [W7++]
0000	000000	NOP
0000	000000	NOP
0000	BBE6B6	TBLWTH.B [W6++], [W7++]
0000	000000	NOP
0000	000000	NOP
0000	BB1BB6	TBLWTL [W6++], [W7++]
0000	000000	NOP
0000	000000	NOP
<b>Step 9:</b> Repeat Steps 7-8 eight times to load the write latches for the 32 instructions.		
<b>Step 10:</b> Unlock the NVMCON for programming.		
0000	200558	MOV #0x55, W8
0000	883B38	MOV W8, NVMKEY
0000	200AA9	MOV #0xAA, W9
0000	883B39	MOV W9, NVMKEY
<b>Step 11:</b> Initiate the programming cycle.		
0000	A8E761	BSET NVMCON, #15
0000	000000	NOP
0000	000000	NOP
—	—	Externally time 'P12a' ms (see <a href="#">Section 13.0 “AC/DC Characteristics and Timing Requirements”</a> )
0000	000000	NOP
0000	000000	NOP
0000	A9E761	BCLR NVMCON, #15
0000	000000	NOP
0000	000000	NOP
<b>Step 12:</b> Reset the device internal PC.		
0000	040100	GOTO 0x100
0000	000000	NOP
<b>Step 13:</b> Repeat Steps 7-12 until all 23 rows of executive memory are programmed.		

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## 13.0 AC/DC CHARACTERISTICS AND TIMING REQUIREMENTS

TABLE 13-1: AC/DC CHARACTERISTICS

AC/DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating Temperature: 25° C is recommended			
Param. No.	Sym	Characteristic	Min	Max	Units	Conditions
D110	VIHH	High Programming Voltage on $\overline{\text{MCLR}}/\text{VPP}$	9.00	13.25	V	—
D112	I <sub>PP</sub>	Programming Current on $\overline{\text{MCLR}}/\text{VPP}$	—	300	μA	—
D113	I <sub>DDP</sub>	Supply Current during programming	—	30	mA	Row Erase Program memory
			—	30	mA	Row Erase Data EEPROM
			—	30	mA	Bulk Erase
D001	V <sub>DD</sub>	Supply voltage	2.5	5.5	V	—
D002	V <sub>DDBULK</sub>	Supply voltage for Bulk Erase programming	4.5	5.5	V	—
D031	V <sub>IL</sub>	Input Low Voltage	V <sub>SS</sub>	0.2 V <sub>SS</sub>	V	—
D041	V <sub>IH</sub>	Input High Voltage	0.8 V <sub>DD</sub>	V <sub>DD</sub>	V	—
D080	V <sub>OL</sub>	Output Low Voltage	—	0.6	V	I <sub>OL</sub> = 8.5 mA
D090	V <sub>OH</sub>	Output High Voltage	V <sub>DD</sub> - 0.7	—	V	I <sub>OH</sub> = -3.0 mA
D012	C <sub>IO</sub>	Capacitive Loading on I/O Pin (PGD)	—	50	pF	To meet AC specifications
P1	T <sub>SCLK</sub>	Serial Clock (PGC) period	50	—	ns	ICSP™ mode
			1	—	μs	Enhanced ICSP mode
P1a	T <sub>SCLKL</sub>	Serial Clock (PGC) low time	20	—	ns	ICSP mode
			400	—	ns	Enhanced ICSP mode
P1b	T <sub>SCLKH</sub>	Serial Clock (PGC) high time	20	—	ns	ICSP mode
			400	—	ns	Enhanced ICSP mode
P2	T <sub>SET1</sub>	Input Data Setup Timer to PGC ↓	15	—	ns	—
P3	T <sub>HLD1</sub>	Input Data Hold Time from PGC ↓	15	—	ns	—
P4	T <sub>DLY1</sub>	Delay between 4-bit command and command operand	20	—	ns	—
P4a	T <sub>DLY1a</sub>	Delay between 4-bit command operand and next 4-bit command	20	—	ns	—
P5	T <sub>DLY2</sub>	Delay between last PGC ↓ of command to first PGC ↑ of VISI output	20	—	ns	—
P6	T <sub>SET2</sub>	V <sub>DD</sub> ↑ setup time to $\overline{\text{MCLR}}/\text{VPP}$	100	—	ns	—
P7	T <sub>HLD2</sub>	Input data hold time from $\overline{\text{MCLR}}/\text{VPP}$ ↑	2	—	μs	ICSP mode
			5	—	ms	Enhanced ICSP mode
P8	T <sub>DLY3</sub>	Delay between last PGC ↓ of command word to PGD driven ↑ by programming executive	20	—	μs	—
P9a	T <sub>DLY4</sub>	Programming Executive Command processing time	10	—	μs	—

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NOTES:

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**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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